


Iesa AG 698-WCG/HCL
6713-St-bb**AMENDMENT TO THE CLAIMS**

Claims 1-8 (cancelled)

Claim 9 (previously amended)

9. Electrically conductive, thermoplastic and heat-activatable adhesive film, comprising

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- i) a thermoplastic polymer in a proportion of from 30 to 89.9% by weight,
 - ii)
 - a) one or more tackifying resins in a proportion of from 5 to 50% by weight or
 - b) epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight, or
 - c) both said one or more tackifying resins in a proportion of from 5 to 50% by weight and said epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight,
 - and
 - iii) silver-coated glass beads in a proportion of from 0.1 to 40% by weight,
 - iv) where the diameter of the glass beads is at least equal to the thickness of the adhesive film.

Claim 10 (previously amended)

10. Adhesive film according to Claim 9, wherein the thermoplastic polymer comprises a member selected from the group consisting of thermoplastic polyolefins, polyesters, polyurethanes or polyamides and modified rubbers.

Claim 11 (previously amended)

11. Adhesive film according to Claim 9, wherein the adhesive film is blended with one or more

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additives.

Claim 12 (previously amended)

12. Thermoplastic adhesive film according to Claim 9, wherein the adhesive film has a thickness of from 20 to 500 μm .

Claim 13 (currently amended)

13. Thermoplastic adhesive film according to Claim 9, wherein the adhesive film ~~is suitable for hot pressing~~ is not pressable at temperatures below 120°C.

Claim 14 (previously amended)

14. Thermoplastic adhesive film comprising

- i) a thermoplastic polymer in a proportion of from 30 to 89.9% by weight,
- ii)
 - a) one or more tackifying resins in a proportion of from 5 to 50% by weight or
 - b) epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight, or
 - c) both said one or more tackifying resins in a proportion of from 5 to 50% by weight and said epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight,

and


- iii) silver-coated glass beads in a proportion of from 0.1 to 40% by weight,
- iv) where the diameter of the glass beads is at least equal to the thickness of the adhesive film, and

wherein the adhesive film is in the form of a punched film section.

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Claim 15 (previously amended)

15. A method for implanting electrical modules in a card body provided with a cutout for accommodating an electronic module which on a first side has a plurality of contact surfaces and on a second side, which is opposite the first side, has an IC chip whose terminals are connected via electrical conductors to the contact surfaces, wherein an electrically conductive, thermoplastic and heat-activatable adhesive film, comprising

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- i) a thermoplastic polymer in a proportion of from 30 to 89.9% by weight,
 - ii)
 - a) one or more tackifying resins in a proportion of from 5 to 50% by weight or
 - b) epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight, or
 - c) both said one or more tackifying resins in a proportion of from 5 to 50% by weight and said epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight,
- and
- iii) silver-coated glass beads in a proportion of from 0.1 to 40% by weight,
 - iv) where the diameter of the glass beads is at least equal to the thickness of the adhesive film is used to connect the second side of the module to the card body.

Claim 16 (cancelled)

Claim 17 (previously amended)

17. The adhesive film of claim 11, wherein said additives are selected from the group consisting of colorants and mineral or organic fillers.

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Claim 18 (previously amended)

18. The adhesive film of claim 17, wherein said additives are selected from the group consisting of silica, carbon powders, and metal powder.

Claim 19 (previously amended)

19. The adhesive film of claim 13, wherein said temperatures are from 80°C to 100°C.

Claim 20 (previously added)

20. The adhesive film of claim 10, wherein said modified rubbers are nitrile rubbers.
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